

In th Sp cification

Amend the title as follows:

~~Methods for Conditioning Surfaces of Polishing Pads After Chemical Mechanical Polishing,~~
and Apparatuses for Conditioning Surfaces of Polishing Pads

RELATED PATENT DATA

This patent resulted from a divisional application of U.S. Patent Application Serial
No. 10/075,172, which was filed February 13, 2002.